

# SOT550-1

plastic ball grid array package; 304 balls; body 31 x 31 x 1.75 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA304
<b>Package type industry code</b>	BGA304
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>JEDEC package outline code</b>	MS-034
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-1-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	30.8	-	31	31.2	mm
E	package width	30.8	-	31	31.2	mm
A	seated height	[tbd]	-	2.54	2.54	mm
A <sub>2</sub>	package height	1.62	-	1.75	1.84	mm
n <sub>2</sub>	actual quantity of termination	-	-	304	-	



2. Package outline

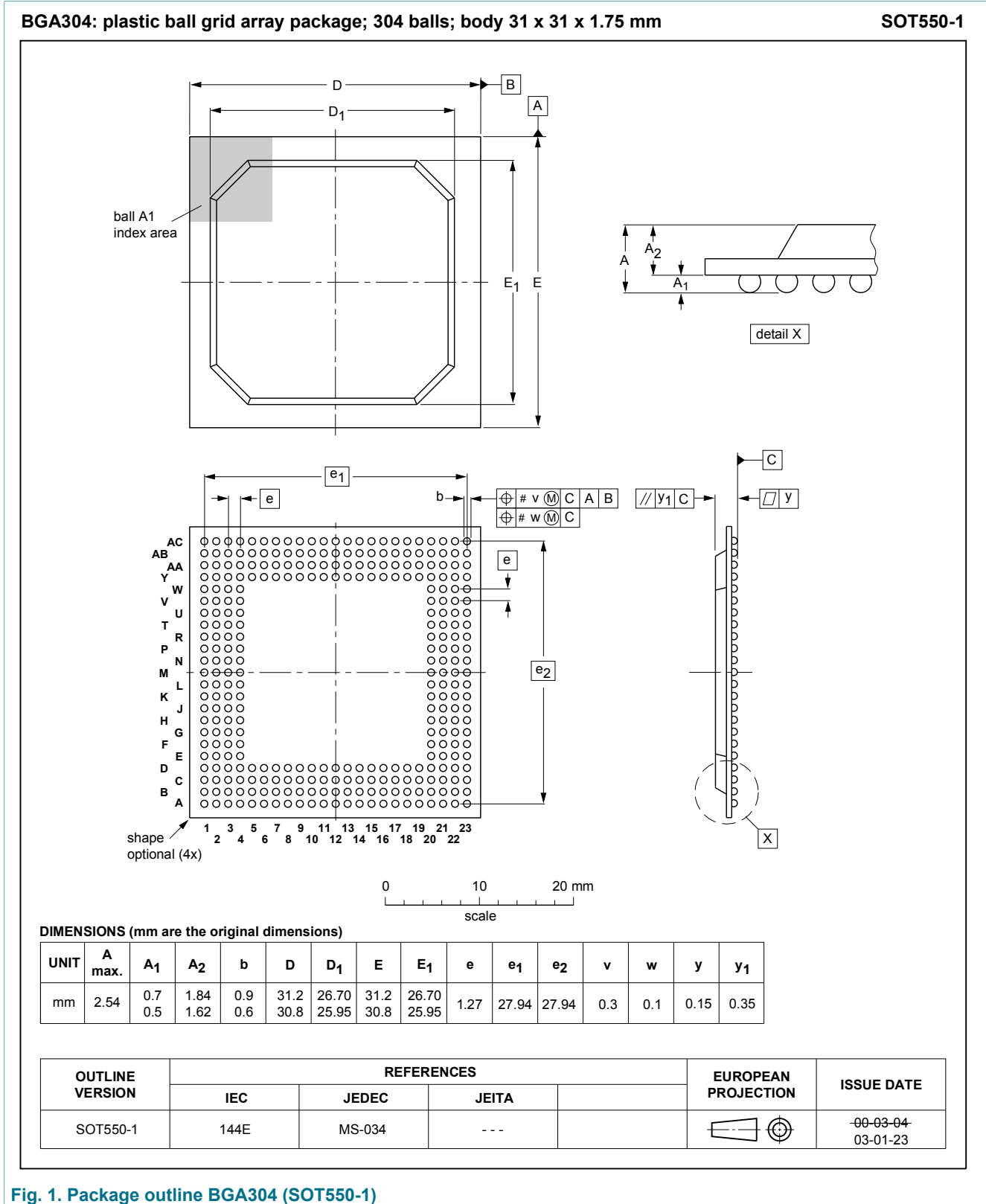


Fig. 1. Package outline BGA304 (SOT550-1)

### 3. Soldering

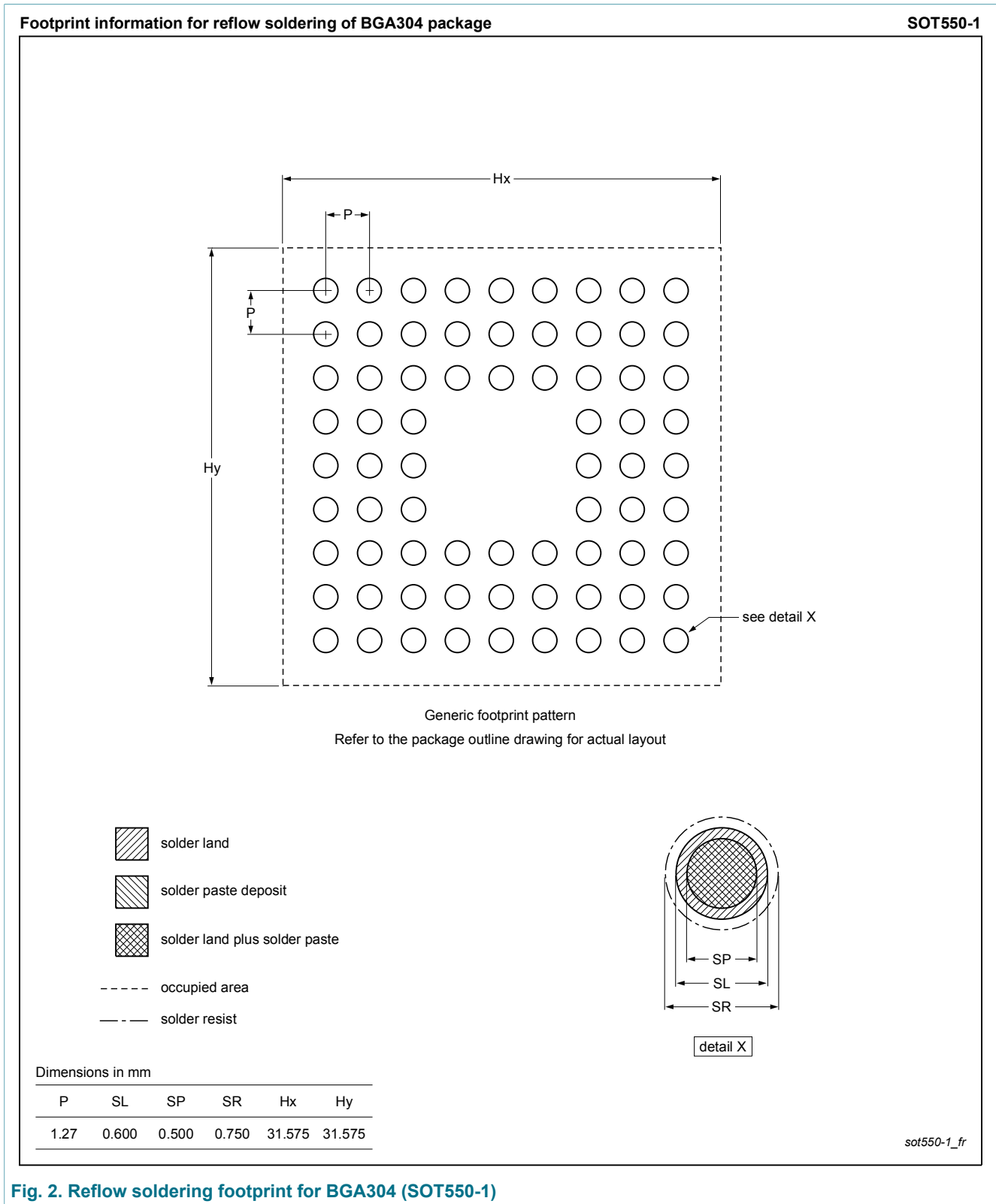


Fig. 2. Reflow soldering footprint for BGA304 (SOT550-1)

## 4. Legal information

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